B SHOULDER

规格书编号 SPEC NO:

产品规格书 SPECIFICATION

CUSTOMER 客户:_			
PRODUCT 产品:_	SAW FILTER		
MODEL NO 型 号:_	HDBF07006D61		
PREPARED 编 制:_		CHECKED 审 核:	Houshihong
APPROVED 批 准:	CHARLES	DATE日期:	2007-01-25

客户确认 CUSTOMER RECEIVED:				
审核 CHECKED	批准 APPROVED	日期 DATE		

无锡市好达电子有限公司 Shoulder Electronics Limited

SAW FILTER

HDBF07006D61

更改历史记录 History Record

更改日期 Date	规格书编号 Spec No	产品型号 Part No	客户产品型号 Customer No	更改内容描述 Modify Content	备注 Remark

SAW FILTER

1. SCOPE

This specification shall cover the characteristics of SAW filter HDBF07006D61

2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-20°C to +55°C
Storage temperature	-45°℃ to +85°℃
RF Power Dissipation	0dBm

Electronic Characteristics

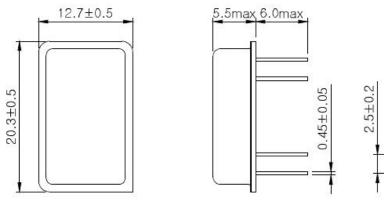
This filter can be used in single-end Input/Output or Balanced.

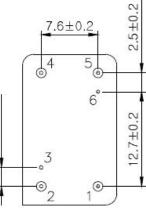
Item	Spec requirement		Unit	
	Min.	Тур.	Max.	
IF center Frequency fo	-	70	-	MHz
Minimum insertion loss attenuation		23	25	dB
1dB Bandwidth	-	6.5	-	MHz
3dB Bandwidth	-	6.8	-	MHz
40dB Bandwidth	-	8.1	-	MHz
$\begin{array}{ll} \text{Amplitude ripple(p-p)} & \Delta \alpha \\ & f_0 \pm 3.125 \text{MHz} \end{array}$	-	0.6	1.0	dB
Group delay ripple fo±3.125MHz	-	70	150	ns
Operating Temperature(°C)	-40		+85	°C
Storage Temperature(°C)	-55		+125	°C
Package	DIP 20x12			mm
f0 frequency shift for all temperature relative to T0 (25°C)			25	kHz

SAW FILTER

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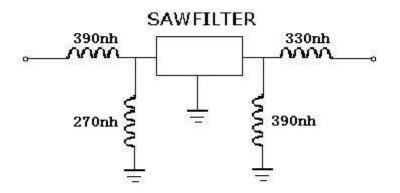
3. DIMENSION





Pin Configur	ation
1	Input
4	Output
2, 5	Ground
Other	Case ground

4.TEST CIRCUIT



HDBF07006D61

SAW FILTER

5. ENVIRONMENTAL CHARACTERISTICS

J-1 mgn temperature exposure	5-1	High	temperature	exposure
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Subject the device to $+85^{\circ}$ C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in table 1.

5-2 Low temperature exposure

Subject the device to -20° C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in table 1.

5-3 Temperature cycling

Subject the device to a low temperature of -40° C for 30 minutes. Following by a high temperature of $+80^{\circ}$ C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in table 1.

5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260° C $\pm 10^{\circ}$ C for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in table 1.

5-5 Solderability

Subject the device terminals into the solder bath at 245° C $\pm 5^{\circ}$ C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in table 1.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in table 1.

5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in table 1.

5-8 Lead fatigue

5-8-1 Pulling test

Weight along with the direction of lead without an shock 1kg. The device shall satisfy all the initial Characteristics.

5-8-2 Bending test

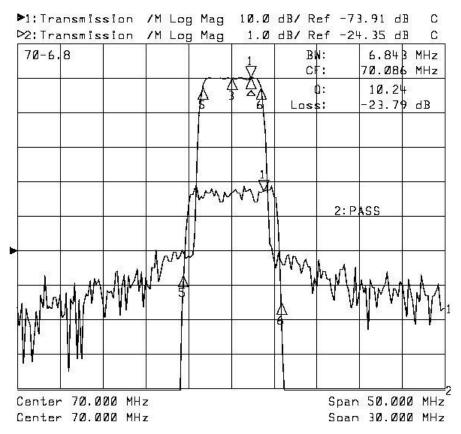
Lead shall be subject to withstand against 90° C bending with 450g weight in the direction of thickness. This operation shall be done toward both direction. The device shall show no evidence of damage and shall satisfy all the initial electrical characteristics.

HDBF07006D61

Typical frequency response

SHOULDER

SAW FILTER



6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.